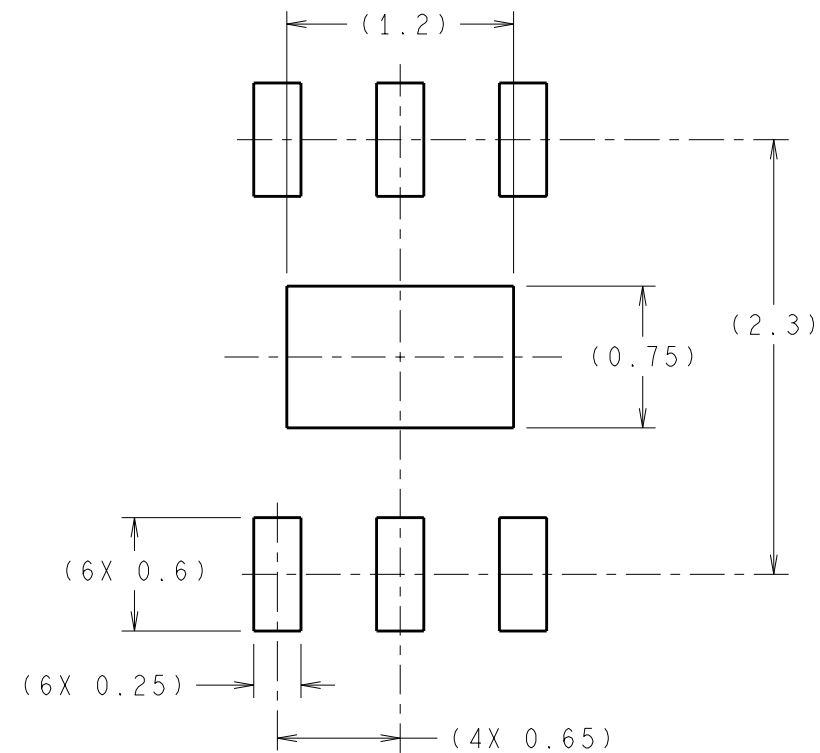
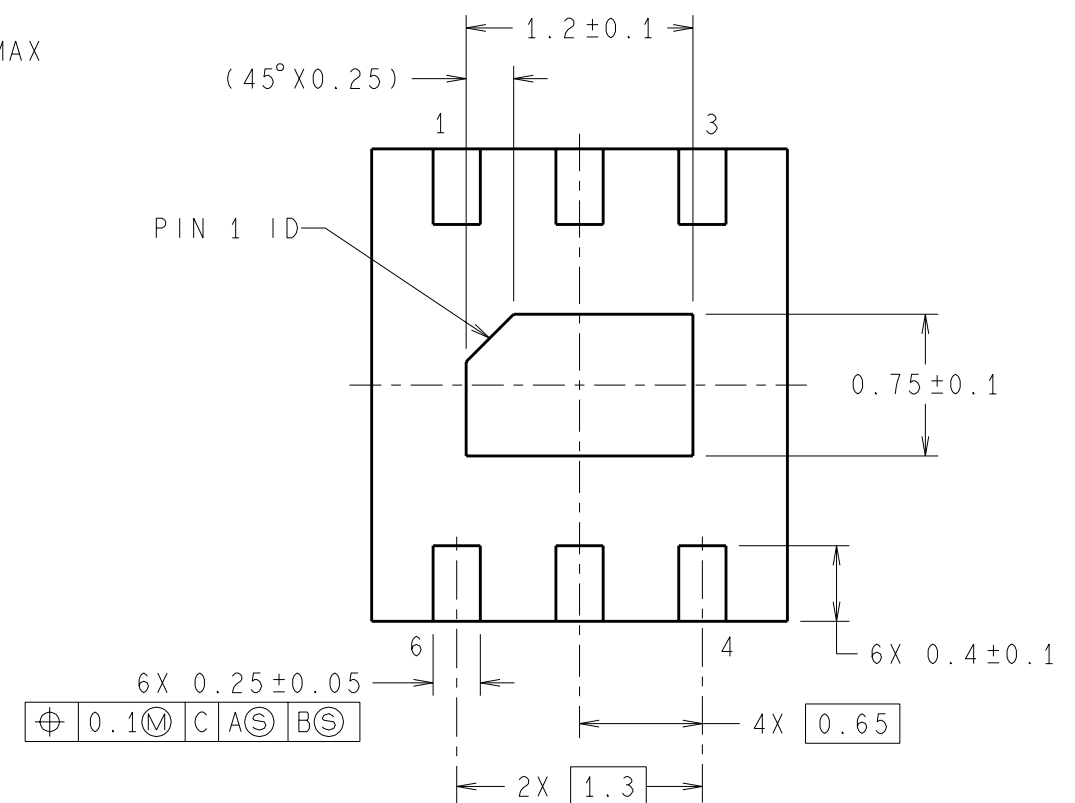
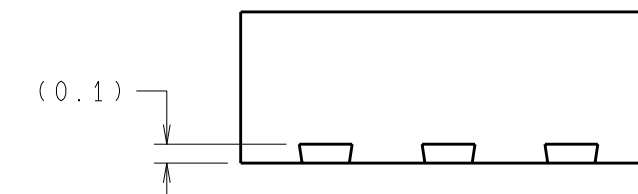
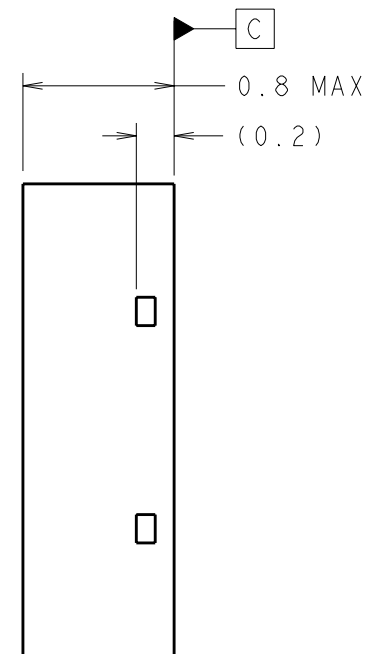
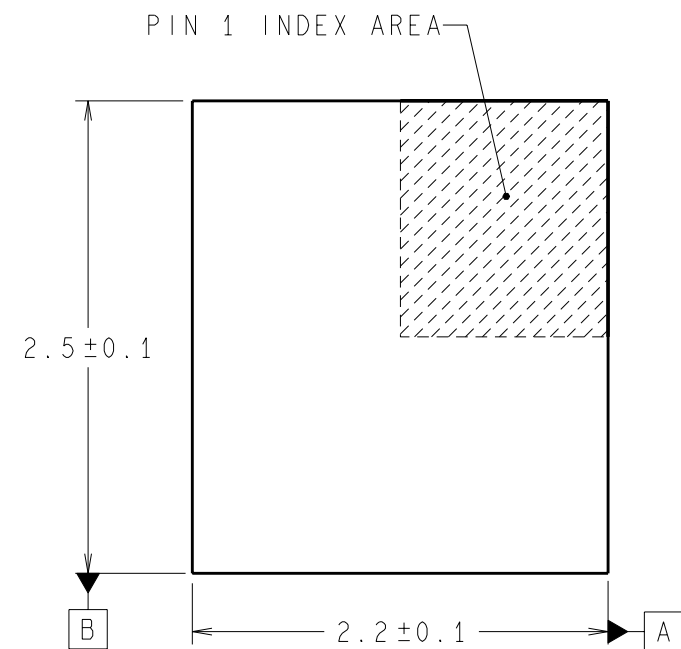


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1192	11/21/2003	AS/MS/SN



DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN () FOR REFERENCE ONLY

RECOMMENDED LAND PATTERN



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- MAXIMUM ALLOWABLE METAL BURR ON LEAD TIPS AT THE PACKAGE EDGES IS 76 MICRONS.
- THIS PACKAGE IS COMPATIBLE WITH SC70 LAND FOOTPRINT ONLY. THE BODY SIZE IS NOT COMPATIBLE WITH 5/6 LEAD SC70.
- NO JEDEC REGISTRATION AS OF NOVEMBER 2003.

APPROVALS		DATE	 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN	ASVOR S. & TL	11/21/2003	
DFTG. CHK.	THANH LEQUANG	11/21/2003	
ENGR. CHK.	N. SANTHIRAN	11/21/2003	
PROJECTION:			LLP, PLASTIC, DUAL, 2.2x2.5x0.8mm BODY, 6 LD, 0.65mm PITCH, NO PULLBACK, SC-70 LAND
SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-SDB06A	A
FORMERLY: N/A			SHEET 1 of 1